

Lecture #7: RF inductors, Transformers (contd.)

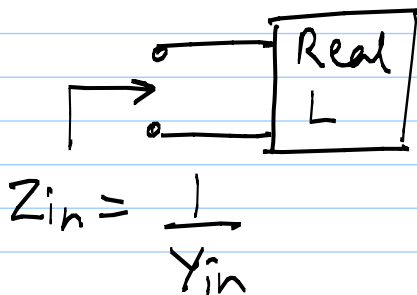
Figures of Merit:

- 1) Q: usually want this to be maximised in the frequency range of interest
— Note that the model is not a simple series or parallel RLC

how is Q determined?

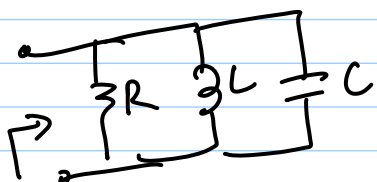
- a) Physical definition: $2\pi \cdot \frac{E_{\text{stored(peak)}}}{E_{\text{loss per cycle}}}$

b)



$$Q = \frac{\text{Im}(Z_{in})}{\text{Re}(Z_{in})} = \frac{\text{Im}(Y_{in})}{\text{Re}(Y_{in})}$$

$$Q = f(L_s, R_s, C_c, C_{ox}, C_{si}, R_{si})$$

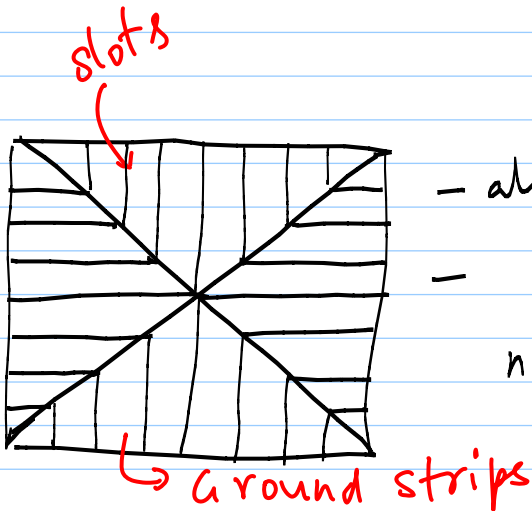


$$Q_{ind} = \frac{\frac{1}{\omega L} - \omega C}{\frac{1}{R}} \quad \left\{ \begin{array}{l} \text{in} \\ \text{inductive} \\ \text{region} \end{array} \right\}$$

* SOI processes show much higher Q than regular CMOS processes

* Substrate losses reduce with distance from substrate — Use highest possible metal
(these are also usually thicker than lower metals)

* Use Patterned Ground Shield, if appropriate
— better Q : a) current loops are broken by slotting — eddy currents \downarrow



— also reduces substrate noise coupling
— more shunt capacitance (shield is now closer than substrate)

2) Self-resonant frequency f_{SR}

— Frequency at which inductance of spiral resonates with its own capacitive parasitics

* Real inductors have capacitive parasitics

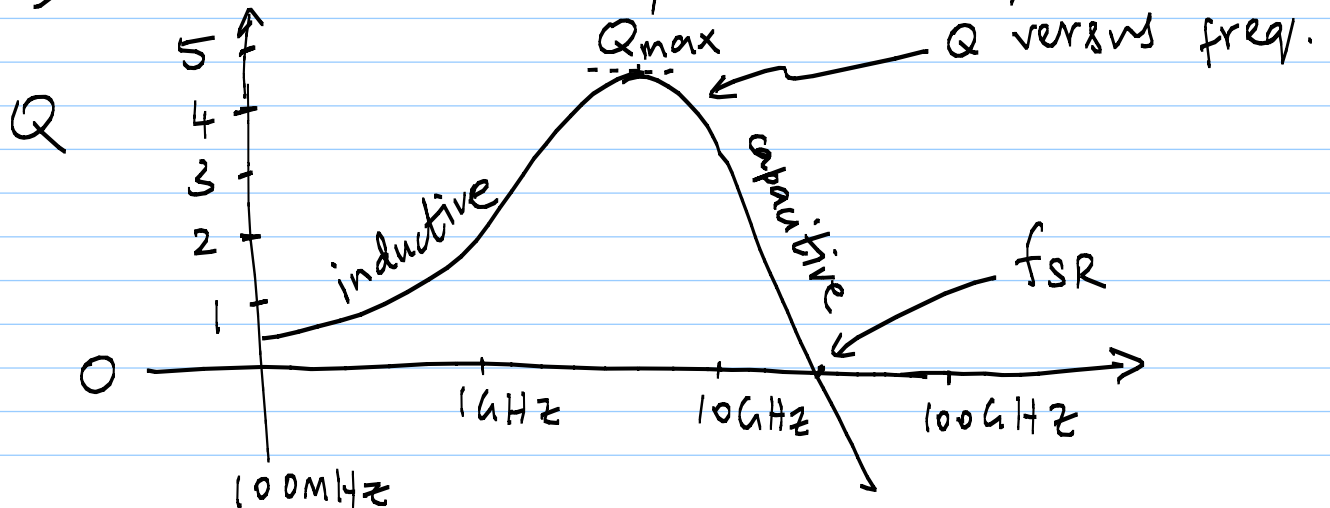
* Real capacitors have inductive parasitics

* Remember — tank circuits have both inductors & capacitors

* Patterned ground shield reduces f_{SR}

- at f_{SR} , inductor impedance is purely resistive, and $Q_{ind} = 0$
- Beyond f_{SR} , the inductor behaves capacitively
- f_{SR} depends on spiral area

3) Total area occupied on chip A



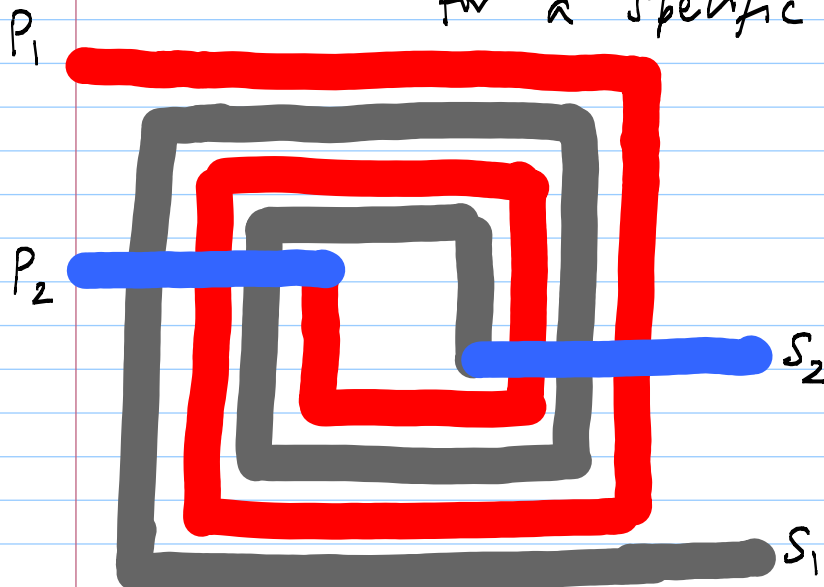
Transformers:

* Used in differential circuits (usually)

* Need to be symmetric

* Coupling factor to be maximised (usually)

- there are cases where you would design for a specific coupling factor

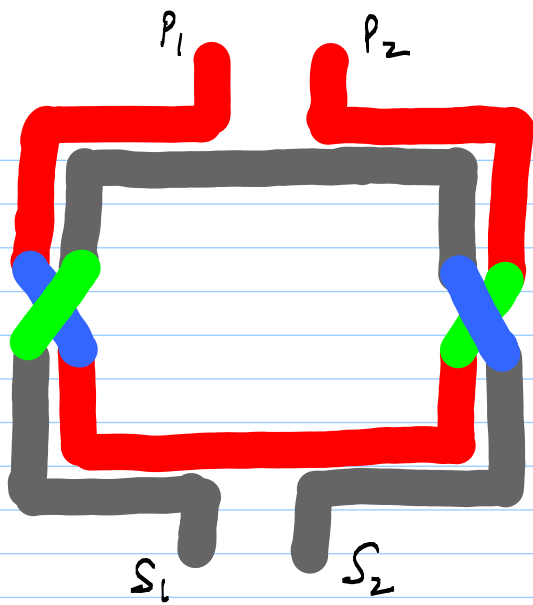


Planar Transformer - 1

* Sideways coupling, $n=2$

* Primary & secondary are symmetric

* Ports P_1 & P_2 (S_1 & S_2) are not symmetric

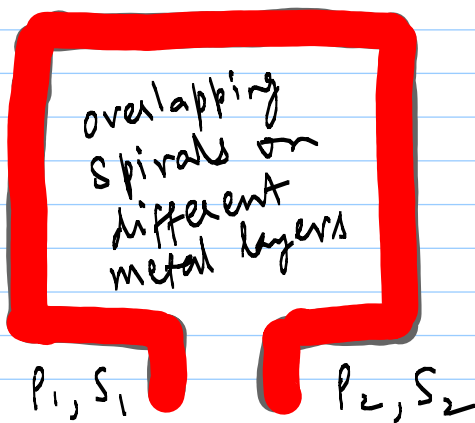


Planar Transformer - 2

* $n=1$

* P & S symmetric

* P_1-P_2 & S_1-S_2 are more symmetric than case 1
 - underpass causes asymmetry

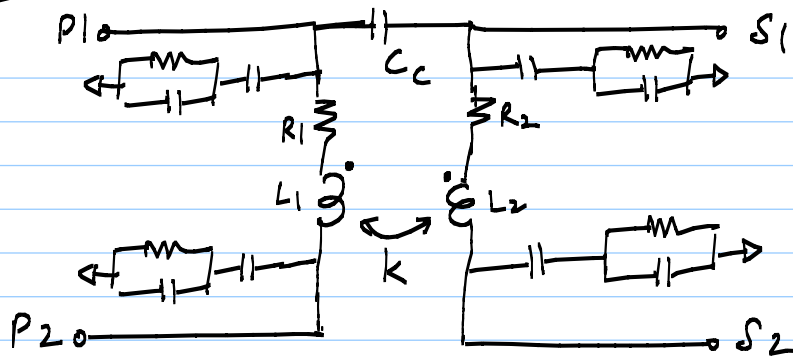


Vertical Transformer

* $n=1$

* P & S are completely asymmetric (different metal layers)

Transformer π -model



* Can cascade coils on multiple metal layers to make a spiral with large L in a given area
 - larger series resistance due to higher R of lower metal layers

- useful to create "RF chokes" for PAs and wideband RF amplifiers

Other Things to remember

- * Overall LC tank Q is often limited by inductor Q
- * Don't place anything close to a spiral (inductor \times fMRI)
- * Use a guard ring around inductor for noise isolation and to provide good EM boundary conditions
- * No metal fill inside inductor (what is this?)
- * maintain symmetry - gives higher Q
- * Via resistance matters - use lots of vias in parallel if you need to change metal layers

Note: * Project 1 will involve spiral inductor design using ASITIC

- * You will be designing your own inductors using ASITIC for projects 2, 3 & 4 also. The design of the inductor will impact circuit performance, so learn this well.
- * HW2 will include an impedance matching problem with a real inductor.